

TECHNICAL DATA SHEET



470-50, 470-1000 PURGE-ATORY Purging Compound

Product Description

Purge-Atory is a revolutionary heavy-duty purging compound. Recommended for use with gas emitting resins such as Delrin & Acetal. Requires no mixing or preparation time. Operating temperatures of 370° - 610°F. Formulated with a SAN resin carrier, Purge-Atory purging compound is safe to purge right through the mold, saving time, material and money. All ingredients are GRAS rated so it is safe to use for food packaging applications. For use with injection molding, extrusion and blow molding.

Applications

Purging Compound

Unit Package Description

50 pound box

Generic Description

Purging Compound

Net Weight Fill

multiple sizes

UPC Code

858799000707

Units Per Case

multiple sizes

Case Weight (lbs)

53

Appearance

Resin Pellet

Flash Point F

>750 degrees

Flash Point C

>400 degrees

Base Type

Resin

Evaporation Rate

N/A

Working Temperature F

370 to 610 degrees

Working Temperature C

187 to 321 degrees

Propellant

N/A

NFPA Aerosol Flammability Level

N/A

DOT Proper Shipping Name

Not regulated, Granules, NOI

VOC % (Federal)

0

VOC g/L (Federal)

0

VOC lbs./Gal (Federal)

0

Removal

N/A